

# Semiconductor Advanced Packaging-Global Market Status and Trend Report 2013-2023

<https://marketpublishers.com/r/S9D561C9549EN.html>

Date: December 2017

Pages: 143

Price: US\$ 2,480.00 (Single User License)

ID: S9D561C9549EN

## Abstracts

### Report Summary

Semiconductor Advanced Packaging-Global Market Status and Trend Report 2013-2023 offers a comprehensive analysis on Semiconductor Advanced Packaging industry, standing on the readers' perspective, delivering detailed market data and penetrating insights. No matter the client is industry insider, potential entrant or investor, the report will provides useful data and information. Key questions answered by this report include:

Worldwide and Regional Market Size of Semiconductor Advanced Packaging 2013-2017, and development forecast 2018-2023

Main manufacturers/suppliers of Semiconductor Advanced Packaging worldwide, with company and product introduction, position in the Semiconductor Advanced Packaging market

Market status and development trend of Semiconductor Advanced Packaging by types and applications

Cost and profit status of Semiconductor Advanced Packaging, and marketing status

Market growth drivers and challenges

The report segments the global Semiconductor Advanced Packaging market as:

Global Semiconductor Advanced Packaging Market: Regional Segment Analysis (Regional Production Volume, Consumption Volume, Revenue and Growth Rate 2013-2023):

North America

Europe

China

Japan

Rest APAC

Latin America

Global Semiconductor Advanced Packaging Market: Type Segment Analysis  
(Consumption Volume, Average Price, Revenue, Market Share and Trend 2013-2023):

FO WLP

2.5D/3D

FI WLP

Flip Chip

Global Semiconductor Advanced Packaging Market: Application Segment Analysis  
(Consumption Volume and Market Share 2013-2023; Downstream Customers and Market Analysis)

CMOS image sensors

Wireless connectivity devices

Logic and memory devices

MEMS and sensors

Analog and mixed ICs

Global Semiconductor Advanced Packaging Market: Manufacturers Segment Analysis  
(Company and Product introduction, Semiconductor Advanced Packaging Sales Volume, Revenue, Price and Gross Margin):

Advanced Semiconductor Engineering

Amkor Technology

Samsung Semiconductor

TSMC

China Wafer Level CSP

ChipMOS TECHNOLOGIES

FlipChip International

HANA Micron

Interconnect Systems (Molex)

Jiangsu Changjiang Electronics Technology (JCET)

King Yuan Electronics

Tongfu Microelectronics  
Nepes  
Powertech Technology (PTI)  
SIGNETICS  
Tianshui Huatian  
Ultratech  
UTAC

In a word, the report provides detailed statistics and analysis on the state of the industry; and is a valuable source of guidance and direction for companies and individuals interested in the market.

## Contents

### **CHAPTER 1 OVERVIEW OF SEMICONDUCTOR ADVANCED PACKAGING**

- 1.1 Definition of Semiconductor Advanced Packaging in This Report
- 1.2 Commercial Types of Semiconductor Advanced Packaging
  - 1.2.1 FO WLP
  - 1.2.2 2.5D/3D
  - 1.2.3 FI WLP
  - 1.2.4 Flip Chip
- 1.3 Downstream Application of Semiconductor Advanced Packaging
  - 1.3.1 CMOS image sensors
  - 1.3.2 Wireless connectivity devices
  - 1.3.3 Logic and memory devices
  - 1.3.4 MEMS and sensors
  - 1.3.5 Analog and mixed ICs
- 1.4 Development History of Semiconductor Advanced Packaging
- 1.5 Market Status and Trend of Semiconductor Advanced Packaging 2013-2023
  - 1.5.1 Global Semiconductor Advanced Packaging Market Status and Trend 2013-2023
  - 1.5.2 Regional Semiconductor Advanced Packaging Market Status and Trend 2013-2023

### **CHAPTER 2 GLOBAL MARKET STATUS AND FORECAST BY REGIONS**

- 2.1 Market Development of Semiconductor Advanced Packaging 2013-2017
- 2.2 Production Market of Semiconductor Advanced Packaging by Regions
  - 2.2.1 Production Volume of Semiconductor Advanced Packaging by Regions
  - 2.2.2 Production Value of Semiconductor Advanced Packaging by Regions
- 2.3 Demand Market of Semiconductor Advanced Packaging by Regions
- 2.4 Production and Demand Status of Semiconductor Advanced Packaging by Regions
  - 2.4.1 Production and Demand Status of Semiconductor Advanced Packaging by Regions 2013-2017
  - 2.4.2 Import and Export Status of Semiconductor Advanced Packaging by Regions 2013-2017

### **CHAPTER 3 GLOBAL MARKET STATUS AND FORECAST BY TYPES**

- 3.1 Production Volume of Semiconductor Advanced Packaging by Types
- 3.2 Production Value of Semiconductor Advanced Packaging by Types

### 3.3 Market Forecast of Semiconductor Advanced Packaging by Types

## **CHAPTER 4 GLOBAL MARKET STATUS AND FORECAST BY DOWNSTREAM INDUSTRY**

### 4.1 Demand Volume of Semiconductor Advanced Packaging by Downstream Industry

### 4.2 Market Forecast of Semiconductor Advanced Packaging by Downstream Industry

## **CHAPTER 5 MARKET DRIVING FACTOR ANALYSIS OF SEMICONDUCTOR ADVANCED PACKAGING**

### 5.1 Global Economy Situation and Trend Overview

### 5.2 Semiconductor Advanced Packaging Downstream Industry Situation and Trend Overview

## **CHAPTER 6 SEMICONDUCTOR ADVANCED PACKAGING MARKET COMPETITION STATUS BY MAJOR MANUFACTURERS**

### 6.1 Production Volume of Semiconductor Advanced Packaging by Major Manufacturers

### 6.2 Production Value of Semiconductor Advanced Packaging by Major Manufacturers

### 6.3 Basic Information of Semiconductor Advanced Packaging by Major Manufacturers

#### 6.3.1 Headquarters Location and Established Time of Semiconductor Advanced Packaging Major Manufacturer

#### 6.3.2 Employees and Revenue Level of Semiconductor Advanced Packaging Major Manufacturer

### 6.4 Market Competition News and Trend

#### 6.4.1 Merger, Consolidation or Acquisition News

#### 6.4.2 Investment or Disinvestment News

#### 6.4.3 New Product Development and Launch

## **CHAPTER 7 SEMICONDUCTOR ADVANCED PACKAGING MAJOR MANUFACTURERS INTRODUCTION AND MARKET DATA**

### 7.1 Advanced Semiconductor Engineering

#### 7.1.1 Company profile

#### 7.1.2 Representative Semiconductor Advanced Packaging Product

#### 7.1.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of Advanced Semiconductor Engineering

### 7.2 Amkor Technology

- 7.2.1 Company profile
- 7.2.2 Representative Semiconductor Advanced Packaging Product
- 7.2.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of Amkor Technology
- 7.3 Samsung Semiconductor
  - 7.3.1 Company profile
  - 7.3.2 Representative Semiconductor Advanced Packaging Product
  - 7.3.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of Samsung Semiconductor
- 7.4 TSMC
  - 7.4.1 Company profile
  - 7.4.2 Representative Semiconductor Advanced Packaging Product
  - 7.4.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of TSMC
- 7.5 China Wafer Level CSP
  - 7.5.1 Company profile
  - 7.5.2 Representative Semiconductor Advanced Packaging Product
  - 7.5.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of China Wafer Level CSP
- 7.6 ChipMOS TECHNOLOGIES
  - 7.6.1 Company profile
  - 7.6.2 Representative Semiconductor Advanced Packaging Product
  - 7.6.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of ChipMOS TECHNOLOGIES
- 7.7 FlipChip International
  - 7.7.1 Company profile
  - 7.7.2 Representative Semiconductor Advanced Packaging Product
  - 7.7.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of FlipChip International
- 7.8 HANA Micron
  - 7.8.1 Company profile
  - 7.8.2 Representative Semiconductor Advanced Packaging Product
  - 7.8.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of HANA Micron
- 7.9 Interconnect Systems (Molex)
  - 7.9.1 Company profile
  - 7.9.2 Representative Semiconductor Advanced Packaging Product
  - 7.9.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of Interconnect Systems (Molex)

## 7.10 Jiangsu Changjiang Electronics Technology (JCET)

### 7.10.1 Company profile

### 7.10.2 Representative Semiconductor Advanced Packaging Product

### 7.10.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of Jiangsu Changjiang Electronics Technology (JCET)

## 7.11 King Yuan Electronics

### 7.11.1 Company profile

### 7.11.2 Representative Semiconductor Advanced Packaging Product

### 7.11.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of King Yuan Electronics

## 7.12 Tongfu Microelectronics

### 7.12.1 Company profile

### 7.12.2 Representative Semiconductor Advanced Packaging Product

### 7.12.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of Tongfu Microelectronics

## 7.13 Nepes

### 7.13.1 Company profile

### 7.13.2 Representative Semiconductor Advanced Packaging Product

### 7.13.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of Nepes

## 7.14 Powertech Technology (PTI)

### 7.14.1 Company profile

### 7.14.2 Representative Semiconductor Advanced Packaging Product

### 7.14.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of Powertech Technology (PTI)

## 7.15 SIGNETICS

### 7.15.1 Company profile

### 7.15.2 Representative Semiconductor Advanced Packaging Product

### 7.15.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of SIGNETICS

## 7.16 Tianshui Huatian

## 7.17 Ultratech

## 7.18 UTAC

## **CHAPTER 8 UPSTREAM AND DOWNSTREAM MARKET ANALYSIS OF SEMICONDUCTOR ADVANCED PACKAGING**

### 8.1 Industry Chain of Semiconductor Advanced Packaging

### 8.2 Upstream Market and Representative Companies Analysis

### 8.3 Downstream Market and Representative Companies Analysis

## **CHAPTER 9 COST AND GROSS MARGIN ANALYSIS OF SEMICONDUCTOR ADVANCED PACKAGING**

- 9.1 Cost Structure Analysis of Semiconductor Advanced Packaging
- 9.2 Raw Materials Cost Analysis of Semiconductor Advanced Packaging
- 9.3 Labor Cost Analysis of Semiconductor Advanced Packaging
- 9.4 Manufacturing Expenses Analysis of Semiconductor Advanced Packaging

## **CHAPTER 10 MARKETING STATUS ANALYSIS OF SEMICONDUCTOR ADVANCED PACKAGING**

- 10.1 Marketing Channel
  - 10.1.1 Direct Marketing
  - 10.1.2 Indirect Marketing
  - 10.1.3 Marketing Channel Development Trend
- 10.2 Market Positioning
  - 10.2.1 Pricing Strategy
  - 10.2.2 Brand Strategy
  - 10.2.3 Target Client
- 10.3 Distributors/Traders List

## **CHAPTER 11 REPORT CONCLUSION**

## **CHAPTER 12 RESEARCH METHODOLOGY AND REFERENCE**

- 12.1 Methodology/Research Approach
  - 12.1.1 Research Programs/Design
  - 12.1.2 Market Size Estimation
  - 12.1.3 Market Breakdown and Data Triangulation
- 12.2 Data Source
  - 12.2.1 Secondary Sources
  - 12.2.2 Primary Sources
- 12.3 Reference



## I would like to order

Product name: Semiconductor Advanced Packaging-Global Market Status and Trend Report 2013-2023

Product link: <https://marketpublishers.com/r/S9D561C9549EN.html>

Price: US\$ 2,480.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:

[info@marketpublishers.com](mailto:info@marketpublishers.com)

## Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page <https://marketpublishers.com/r/S9D561C9549EN.html>

To pay by Wire Transfer, please, fill in your contact details in the form below:

First name:  
Last name:  
Email:  
Company:  
Address:  
City:  
Zip code:  
Country:  
Tel:  
Fax:  
Your message:

**\*\*All fields are required**

Customer signature \_\_\_\_\_

Please, note that by ordering from marketpublishers.com you are agreeing to our Terms & Conditions at <https://marketpublishers.com/docs/terms.html>

To place an order via fax simply print this form, fill in the information below and fax the completed form to +44 20 7900 3970